

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/15/2022

Details for "SN74LV174ADE4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN74LV174ADE4	NIPDAU	Level-1-260C-UNLIM	TI AGUASCALIENTES	D 16	3.91x9.9x1.58	194.5

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.0758	99.998681	999987	0.038978	390
Precious Metals	Silver	7440-22-4	0.000001	0.001319	13	0.000001	0
Sub-Total			0.075801	100	1000000	0.038979	390
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.17152	78.999972	790000	0.0882	882
Thermoplastics	Epoxy	85954-11-6	0.045594	21.000028	210000	0.023446	234
Sub-Total			0.217114	100	1000000	0.111646	1116
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	79.065844	97.24	972400	40.657701	406577
Copper and Its Alloys	Iron	7439-89-6	2.11406	2.6	26000	1.087104	10871
Copper and Its Alloys	Phosphorus	7723-14-0	0.121965	0.15	1500	0.062718	627
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.008131	0.01	100	0.004181	42
Sub-Total			81.31	100	1000000	41.811704	418117
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.66584	95.12	951200	0.342392	3424
Precious Metals	Gold	7440-57-5	0.00546	0.78	7800	0.002808	28
Precious Metals	Palladium	7440-05-3	0.0287	4.1	41000	0.014758	148
Sub-Total			0.7	100	1000000	0.359958	3600
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	98.009671	88	880000	50.399107	503991
Other Plastics and Rubber	Carbon Black	1333-86-4	0.334124	0.3	3000	0.171815	1718
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.61256	0.55	5500	0.314994	3150
Thermoplastics	Epoxy	85954-11-6	12.418271	11.15	111500	6.385796	63858
Sub-Total			111.374626	100	1000000	57.271712	572717
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.789538	100	1000000	0.406001	4060
Sub-Total			0.789538	100	1000000	0.406001	4060
Total			194.467079			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. [See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMIS or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." [For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide [Sb203] contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.